



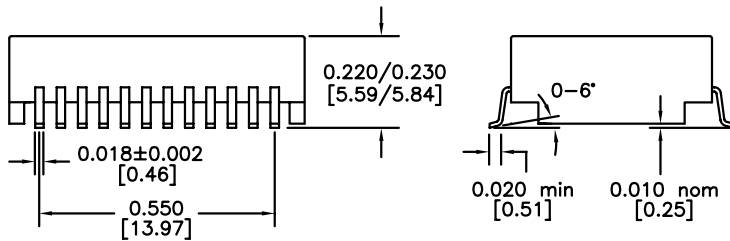
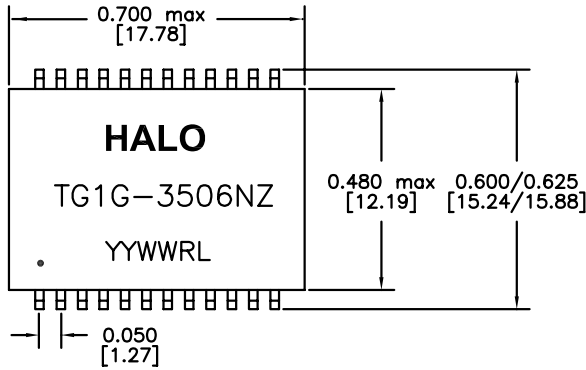
PART NO. : TG1G-3506NZRL

SMT ISOLATION MODULE FOR 1000BASE-T,
 IEEE802.3ab APPLICATIONS

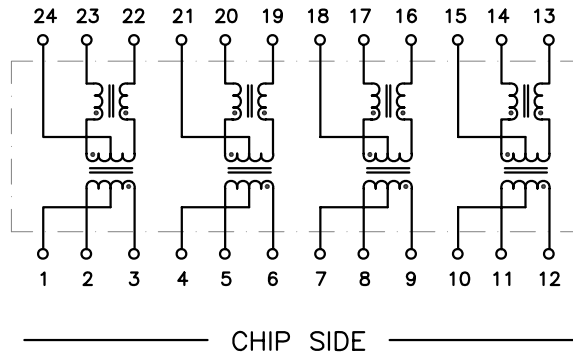
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
 CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C



DIMENSIONS: Inch [mm]
 CO-PLANARITY: 0.004 [0.10]
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO	1CT:1CT ±2%
OCL (100KHz,0.1Vrms,8mA)	350µH min
DCR (CHIP SIDE)	0.9Ω max
INSERTION LOSS	
1-100MHz	-1.1dB max
RETURN LOSS	
1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK	
1-100MHz	-40dB typ
CMR	
0.1-100MHz	-40dB typ
ISOLATION	1,500Vrms



HALO/PBL

CALIFORNIA, USA
 KOWLOON, HONG KONG
 SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
FOR	1000BASE-T	DRAWN	LI ZHI ZHONG	7/1/05	A	FIRST ISSUE
PART NO.	TG1G-3506NZRL	CHECKED	LEI KEONG	8/31/10	B	PROD. RELEASE
SCALE	NONE	APPROVED	PETER LU	8/31/10		
PAGE	1 OF 1	FILE	3506NZRL.DWG			